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(5-2008)



High Stability - High Temperature (230 °C) Thin Film Wraparound Chip Resistors, Sulfur Resistant



INTRODUCTION

For applications such as down hole applications, the need for parts able to withstand very severe conditions (temperature as high as 215 °C powered or up to 230 °C un-powered) has leaded Vishay Sfernice to push out the limit of the thin film technology.

Designers might read the application note: Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chip Resistors and Arrays (P, PRA etc...) (High Temperature Application) www.vishay.com/doc?53047 in conjunction with this datasheet to help them to properly design their PCBs and get the best performances of the PHT.

Vishay Sfernice R&D engineers will be willing to support any customer design considerations.

FEATURES

- Operating temperature range: -55 °C; +215 °C
- Storage temperature: -55 °C; +230 °C
- Gold terminations (< 1 µm thick)
- 5 sizes available (0402, 0603, 0805, 1206, 2010); other sizes upon request
- Temperature coefficient down to 15 ppm (-55 °C; +215 °C)
- Tolerance down to 0.01 %
- Load life stability: 0.35 % max. after 2000 h at 220 °C (ambient) at Pn
- Shelf life stability: 0.7 % typ. (1 % max.) after 15 000 h at 230 °C
- SMD wraparound
- TCR remains constant after long term storage at 230 °C (15 000 h)
- Sulfur resistant (per ASTM B809-95 humid vapor test)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

STANDARD ELECTRICAL SPECIFICATIONS							
MODEL	SIZE	RESISTANCE RANGE Ω	P _{215 °C} W	LIMITING ELEMENT VOLTAGE V	TOLERANCE ⁽²⁾ ± %	TEMPERATURE COEFFICIENT ⁽³⁾ ± ppm/°C	
PHT0402	0402	10 to 130K	0.0189	50	0.01, 0.02, 0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55	
PHT0603	0603	10 to 320K	0.0375	75	0.01, 0.02, 0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55	
PHT0805	0805	10 to 720K	0.06	150	0.01, 0.02, 0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55	
PHT1206	1206	10 to 2.7M	0.1	200	0.01, 0.02, 0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55	
PHT2010	2010	10 to 7.5M	0.2 (4)	300	0.01, 0.02, 0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55	

Notes

- (1) For power handling improvement, please refer to application note 53047: "Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chip Resistors and Arrays (High Temperature Applications)" www.vishay.com/doc?/53047 and consult Vishay Sfernice
- (2) See Table 2 on next page
- (3) See Table 1 on next page
- (4) It is possible to dissipate up to 0.3 W, but there will be an additional drift of 0.1 % after load life

CLIMATIC SPECIFICATIONS					
Operating temperature range	-55 °C; +215 °C				
Storage temperature range	-55 °C; +230 °C				

PERFORMANCE VS. HUMID SULFUR VAPOR					
Test conditions	50 °C ± 2 °C, 85 % ± 4 % RH, exposure time 500 h				
Test results	Resistance drift $<$ (0.05 % R + 0.05 Ω), no corrosion products observed				

MECHANICAL SPECIFICATIONS				
Substrate Alumina				
Resistive Element	Nichrome (NiCr)			
Passivation	Silicon nitride (Si ₃ N ₄)			
Protection	Epoxy + silicone			
Terminations	Gold (< 1 µm) over nickel barrier			

Note

• For other terminations, please consult

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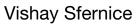
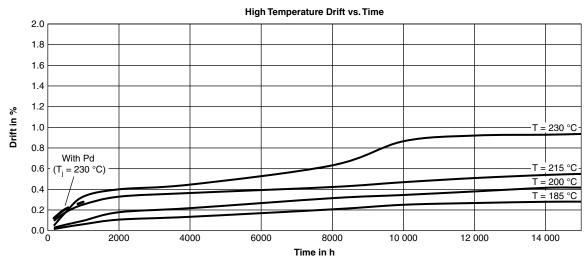




TABLE 1 - TEMPERATURE COEFFICIENT					
V	10 ppm/°C	-55 °C; +155 °C			
T	15 ppm/°C	-55 °C; +215 °C			
E	25 ppm/°C	-55 °C; +155 °C			
-	30 ppm/°C	-55 °C; +215 °C			
Н	50 ppm/°C	-55 °C; +155 °C			
П	55 ppm/°C	-55 °C; +215 °C			

TABLE 2 - BEST TOLERANCE AND TCR VS. OHMIC VALUE					
SERIES	RANGE (Ω)	TOL. (± %)	TCR CODE		
	10 to < 100	0.05; 0.1; 0.5; 1	Y; E; H		
0402	100 to < 90K	0.01; 0.02; 0.05; 0.1; 0.5; 1	Y; E; H		
	90K to 130K	0.01; 0.02; 0.05; 0.1; 0.5; 1	E; H		
	10 to < 100	0.05; 0.1; 0.5; 1	Y; E; H		
0603	100 to < 210K	0.01; 0.02; 0.05; 0.1; 0.5; 1	Y; E; H		
	210K to 320K	0.01; 0.02; 0.05; 0.1; 0.5; 1	E; H		
	10 to < 100	0.05; 0.1; 0.5; 1	Y; E; H		
0805	100 to < 480K	0.01; 0.02; 0.05; 0.1; 0.5; 1	Y; E; H		
	480K to 720K	0.01; 0.02; 0.05; 0.1; 0.5; 1	E; H		
	10 to < 100	0.05; 0.1; 0.5; 1	Y; E; H		
1206	100 to < 1.8M	0.01; 0.02; 0.05; 0.1; 0.5; 1	Y; E; H		
	1.8M to 2.7M	0.01; 0.02; 0.05; 0.1; 0.5; 1	E; H		
	10 to < 100	0.05; 0.1; 0.5; 1	Y; E; H		
2010	100 to < 5M	0.01; 0.02; 0.05; 0.1; 0.5; 1	Y; E; H		
	5M to 7.5M	0.01; 0.02; 0.05; 0.1; 0.5; 1	E; H		

PHT STABILITY CURVE

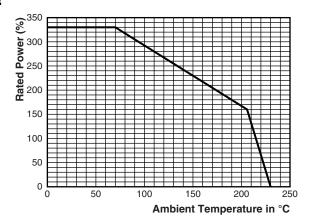


Note

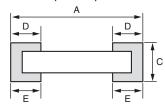
• Stability will be dependent on resistivity of resistor. Above curves are worst case.

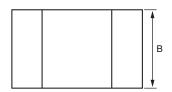


POWER DERATING CURVE



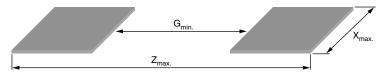
DIMENSIONS in millimeters (inches)





	A B					
CASE SIZE	MAX. TOL. +0.152 (+0.006) MIN. TOL. -0.152 (-0.006)	MAX. TOL. +0.127 (+0.005) MIN. TOL. -0.127 (-0.005)	С	D/E		
	NOMINAL	NOMINAL		NOMINAL	TOLERANCE	
0402	1.00 (0.039)	0.60 (0.024)	Termination N:	0.25 (0.010)	0.1 (0.004)	
0603	1.52 (0.060)	0.85 (0.033)	0.5 (0.02) ± 0.127 (0.005)	0.38 (0.015)		
0805	1.91 (0.075)	1.27 (0.050)	, ,	0.36 (0.013)	0.12 (0.005)	
1206	3.06 (0.120)	1.60 (0.063)	Termination G: 0.4 (0.016)	0.40 (0.016)	0.13 (0.005)	
2010	5.08 (0.200)	2.54 (0.100)	± 0.051 (0.002)	0.48 (0.019)		

SUGGESTED LAND PATTERN (TO IPC-7351A)



CHIP SIZE	DIMENSIONS (in millimeter)				
CHIP SIZE	Z _{max} .	G _{min.}	X _{max.}		
0402	1.55	0.15	0.73		
0603	2.37	0.35	0.98		
0805	2.76	0.74	1.40		
1206	3.91	1.85	1.73		
2010	5.93	3.71	2.67		

Caution:

Performances obtained with following mounting conditions:

PCB: polyimide

Solder paste: PbSnAg (93.5/5/1.5)





POPULAR OPTIONS

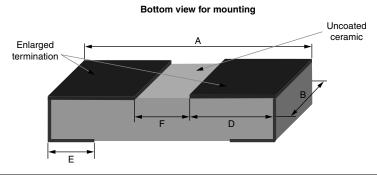
It is recommended to consult Vishay Sfernice for availability first.

Option: Enlarged terminations:

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heatsink (see application note: 53048 "Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film)" www.vishay.com/doc?53048.

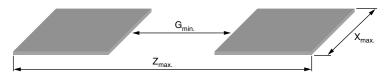
Option to order: 0063 (applies to size 1206 / 2010).

DIMENSIONS (Option 0063) in millimeters



	Α	В	E	D			
CASE SIZE	MAX. TOL. +0.152 MIN. TOL. -0.152	MAX. TOL. +0.127 MIN. TOL. -0.127	MAX. TOL. +0.13 MIN. TOL. -0.13	MAX. TOL. +0.13 MIN. TOL. -0.13		F	
	NOMINAL	NOMINAL	NOMINAL	NOMINAL	NOMINAL	MIN.	MAX.
1206	3.06	1.60	0.40	1.215	0.63	0.50	0.76
2010	5.08	2.54	0.48	2.25	0.03	0.50	0.70

SUGGESTED LAND PATTERN (Option 0063)



CHIP SIZE	DIMENSIONS (in millimeter)				
CHIP SIZE	Z _{max.}	G _{min.}	X _{max.}		
1206	1206 3.91		1.73		
2010	5.93	0.50	2.67		



PACKAGING

ESD packaging available: waffle-pack and plastic tape and reel (low conductivity). Paper tape available in standard (for size 0402) and upon request (ESD only) (for sizes 0603, 0805, and 1206).

		NUMBER OF PIE			
SIZE	MOQ	WAFFLE PACK	TAPE A	TAPE WIDTH	
		2" × 2"	MIN.	MAX.	****
0402				5000	8 mm
0603		100			
0805	100		100	4000	0 111111
1206		140		4000	
2010		60		2000	8 mm ⁽¹⁾

Note

(1) 12 mm on request

PACKAGING RULES

Waffle Pack

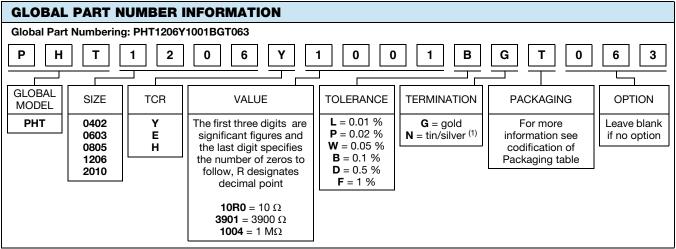
Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover.

To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code.

Tape and Reel

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided.

When several reels are needed for ordered quantity within MOQ and maximum reel capacity: please consult Vishay Sfernice for specific ordering code.



Note

(1) For usage at temperatures up to 200 °C maximum N (tin/silver termination are available upon request)

CODIFICATION OF PACKAGING					
CODE 18	PACKAGING				
WAFFLE PACK					
W	100 min., 1 mult				
WA	100 min., 100 mult (available only on size 1206)				
PLASTIC TAPE (in standard for a	Il sizes except 0402)				
Т	100 min., 1 mult				
TA	100 min., 100 mult				
ТВ	250 min., 250 mult				
TC	500 min., 500 mult				
TD	1000 min., 1000 mult				
TE	2500min., 2500 mult				
TF	Full tape (quantity depending on size of chips)				
PAPER TAPE (in standard for 0402, option for other sizes)					
PT	100 min., 1 mult				
PA	100 min., 100 mult				
PB	250 min., 250 mult				
PC	500 min., 500 mult				
PD	1000 min., 1000 mult				
PE	2500min., 2500 mult				
PF	Full tape (quantity depending on size of chips)				

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 PHT0603Y3003BGT
 PHT2010Y1002BGT
 PHT0805Y5003BGT
 PHT2010Y1001BGT

 PHT1206Y1002BGT
 PHT0805Y1000BGT
 PHT2010Y3004BGT
 PHT0603Y1001BGT
 PHT0603Y1001BGT

 PHT0603Y1002BGT
 PHT0603E10R0DGT
 PHT0805E10R0DGT
 PHT1206E10R0DGT
 PHT2010E10R0DGT

 PHT0805Y5003BGT200
 PHT0603Y1001BGT200
 PHT0603Y4992BGT
 PHT1206Y1001BNT
 PHT0402E1001BGPT

 PHT0402E2002BGPT
 PHT0402E5602BGPT
 PHT0603Y1002BGT118
 PHT2010Y2001BGT